

0.6-3V_{IN}, 1.8-3.6V_{OUT}, 3.5μA, High-Efficiency Boost + Output Load Switch

FEATURES

- Combines Low-power Boost + Output Load Switch
- ♦ Boost Regulator
 - Input Voltage: 0.6V- 3VOutput Voltage: 1.8V- 3.6V
 - Efficiency: Up to 84%
 - No-load Input Current: 3.5µA
 - Delivers >100mA at 1.8V_{BO} from 1.2V_{BI}
 - Boost Shutdown Control
 - · No External Schottky Diode Required
- Anti-Crush Capability
 - Prevents Input Voltage Collapse when powered with Weak/High Impedance Power Sources
- Single-Inductor, Discontinuous Conduction Mode Scheme with Automatic Peak Current Adjustment
- 16-Pin, Low-Profile, Thermally-Enhanced
 3mm x 3mm TQFN Package

APPLICATIONS

Coin Cell-Powered Portable Equipment
Single Cell Li-ion or Alkaline Powered Equipment
Solar or Mechanical Energy Harvesting
Wireless Microphones
Wireless Remote Sensors
RFID Tags
Blood Glucose Meters
Personal Health-Monitoring Devices

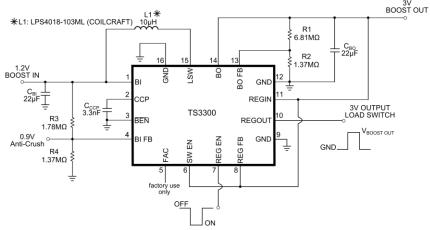
DESCRIPTION

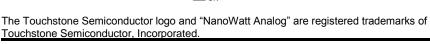
The TS3300 is a 1st-generation Touchstone Semi power management product that combines a high-efficiency boost regulator and an output load switch in one package. The boost regulator operates from a supply voltage as low as 0.6V and can deliver at least 75mA at $1.2V_{BI}$ to $3V_{BO}$, an industry first.

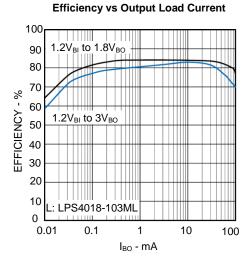
The TS3300 includes an *anti-crush*TM feature to prevent the collapse of the input voltage to the boost regulator when the input is a weak (high impedance) source. If the input voltage drops below a determined voltage threshold (settable by a resistor divider), the boost regulator switching cycles are paused, effectively limiting the minimum input voltage. *Anti-crush*TM is useful in applications where a buffer capacitor at the boost's output can service burst loads, and the input source exhibits substantial source impedance (such as an old battery, or at cold temperatures).

The TS3300 is fully specified over the -40°C to +85°C temperature range and is available in a low-profile, thermally-enhanced 16-pin 3x3mm TQFN package with an exposed back-side paddle. For best performance, solder the exposed back-side paddle to PCB ground.

TYPICAL APPLICATION CIRCUIT

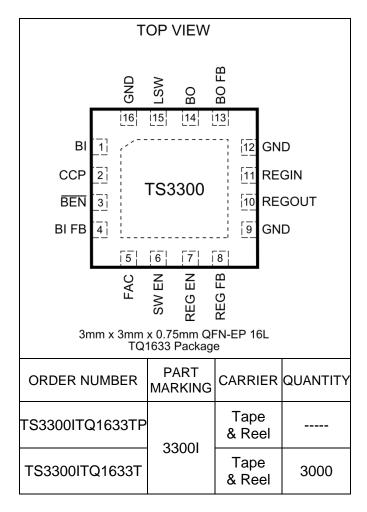








PACKAGE/ORDERING INFORMATION



Lead-free Program: Touchstone Semiconductor supplies only lead-free packaging.

Consult Touchstone Semiconductor for products specified with wider operating temperature ranges.

Information furnished by Touchstone Semiconductor is believed to be accurate and reliable. However, Touchstone Semiconductor does not assume any responsibility for its use nor for any infringements of patents or other rights of third parties that may result from its use, and all information provided by Touchstone Semiconductor and its suppliers is provided on an AS IS basis, WITHOUT WARRANTY OF ANY KIND. Touchstone Semiconductor reserves the right to change product specifications and product descriptions at any time without any advance notice. No license is granted by implication or otherwise under any patent or patent rights of Touchstone Semiconductor. Touchstone Semiconductor assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using Touchstone Semiconductor components. To minimize the risk associated with customer products and applications, customers should provide adequate design and operating safeguards. Trademarks and registered trademarks are the property of their respective owners.